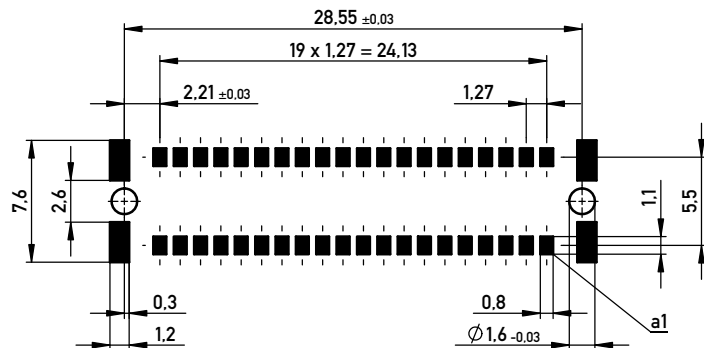
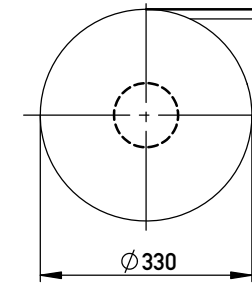


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 280 Stück  
Packaging unit: 280 pcs



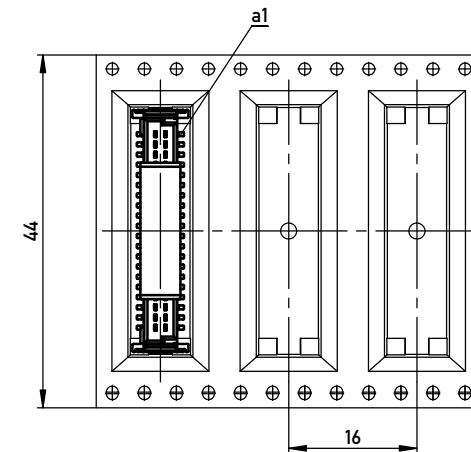
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

Abspulrichtung - Reel off Direction



BA 8-13 - 8mm Bauhöhe  
type 8-13 - Low Profile

Information:		Tolerances	Scale 3:1	Designation	
All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.		 All Dimensions in mm	 Subject to modification without prior notice. Drawing will not be updated.	<b>Messerl. SMC-Q 40-SMD-BA8-13</b> <b>Male SMC-Q 40-SMD-type8-13</b>	
e	14.07.2015	www.ERNI.com		254590	I
Index	Date	Class		SMCQ	A3

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